

Lonten N-channel 120V, 335A, 2.2mΩ Power MOSFET

Description

These N-channel enhancement mode power field effect transistors are using **shielded gate trench** DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- 120V, 335A, $R_{DS(on),max}=2.2\text{m}\Omega$ @ $V_{GS} = 10\text{V}$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green device available

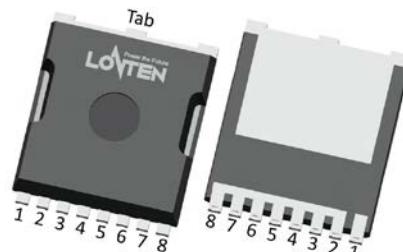
Applications

- Motor Drives
- UPS
- DC-DC Converter
- SR
- BMS

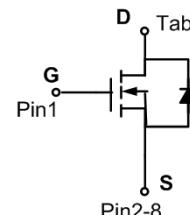
Product Summary

V_{DSS}	120V
$R_{DS(on),typ}$ @ $V_{GS}=10\text{V}$	1.75mΩ
I_D	335A

Pin Configuration



TOLL



N-channel MOSFET



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	120	V
Continuous drain current ¹⁾ $(T_C = 25^\circ\text{C}, \text{Silicon limit})$		335	A
$(T_C = 25^\circ\text{C}, \text{Package limit})$	I_D	372	A
$(T_C = 100^\circ\text{C}, \text{Silicon limit})$		212	A
Pulsed drain current ²⁾	I_{DM}	1340	A
Gate-Source voltage	V_{GS}	± 20	V
Avalanche energy ³⁾	E_{AS}	1521	mJ
Power Dissipation	P_D	481	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.26	°C/W
Thermal Resistance, Junction-to-Ambient, minimal footprint ⁴⁾	$R_{\theta JA}$	62	°C/W
Soldering temperature, wave soldering only allowed at leads. (1.6mm from case for 10s)	T_{sold}	260	°C

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel
LSGT12R022	TOLL	LSGT12R022	2000

Electrical Characteristics
 $T_J = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	120	---	---	V
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	2.5	3.4	4.5	V
Drain-source leakage current	I_{DSS}	$V_{\text{DS}}=120 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_J = 25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=120 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_J = 150^\circ\text{C}$	---	---	100	μA
Gate leakage current, Forward	I_{GSSF}	$V_{\text{GS}}=20 \text{ V}, V_{\text{DS}}=0 \text{ V}$	---	---	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{\text{GS}}=-20 \text{ V}, V_{\text{DS}}=0 \text{ V}$	---	---	-100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=50 \text{ A}, T_J = 25^\circ\text{C}$	---	1.75	2.2	$\text{m}\Omega$
		$T_J = 150^\circ\text{C}$	---	3.34	---	
Forward transconductance	g_{fs}	$V_{\text{DS}}=20 \text{ V}, I_{\text{D}}=50 \text{ A}$	---	127.7	---	S
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}}=60 \text{ V}, V_{\text{GS}}=0 \text{ V}, f = 100 \text{ kHz}$	---	10066	---	pF
Output capacitance	C_{oss}		---	3288	---	
Reverse transfer capacitance	C_{rss}		---	50	---	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}}=60 \text{ V}, V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=50 \text{ A}, R_g = 10 \Omega$	---	116.2	---	ns
Rise time	t_r		---	145.3	---	
Turn-off delay time	$t_{\text{d(off)}}$		---	108.7	---	
Fall time	t_f		---	43.2	---	
Gate resistance	R_g	$V_{\text{GS}}=0 \text{ V}, V_{\text{DS}}=0 \text{ V}, f=1 \text{ MHz}$	---	0.99	---	Ω
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{\text{DS}}=60 \text{ V}, I_{\text{D}}=50 \text{ A}, V_{\text{GS}}=10 \text{ V}$	---	53.4	---	nC
Gate to drain charge	Q_{gd}		---	27.5	---	
Gate charge total	Q_g		---	140.4	---	
Gate plateau voltage	V_{plateau}		---	5.5	---	V
Output Charge	Q_{oss}	$V_{\text{DS}}=120 \text{ V}, V_{\text{GS}}=0 \text{ V}$	---	421	---	nC
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I_s		---	---	335	A
Pulsed Source Current	I_{SM}		---	---	1340	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0 \text{ V}, I_{\text{S}}=50 \text{ A}, T_J=25^\circ\text{C}$	---	---	1.1	V
Peak reverse recovery current	I_{rrm}	$I_{\text{S}}=50 \text{ A}, \text{di/dt}=100 \text{ A/us}, T_J=25^\circ\text{C}$	---	3.87	---	A
Reverse Recovery Time	t_{rr}		---	93.3	---	ns
Reverse Recovery Charge	Q_{rr}		---	228.7	---	nC

Notes:

1. Limited by maximum junction temperature and duty cycle.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3. $V_{\text{DD}}=50 \text{ V}, V_{\text{GS}}=10 \text{ V}, L=0.5 \text{ mH}, I_{\text{AS}}=78 \text{ A}$, Starting $T_J=25^\circ\text{C}$.
4. The value of R_{thJA} is measured by placing the device in a still air box which is one cubic foot.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

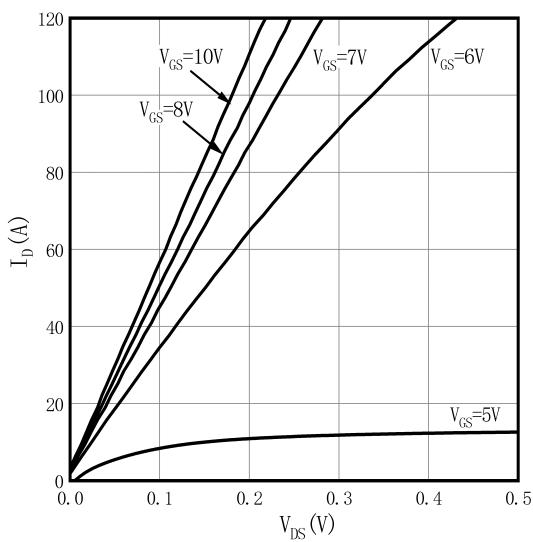


Figure 2. Transfer Characteristics

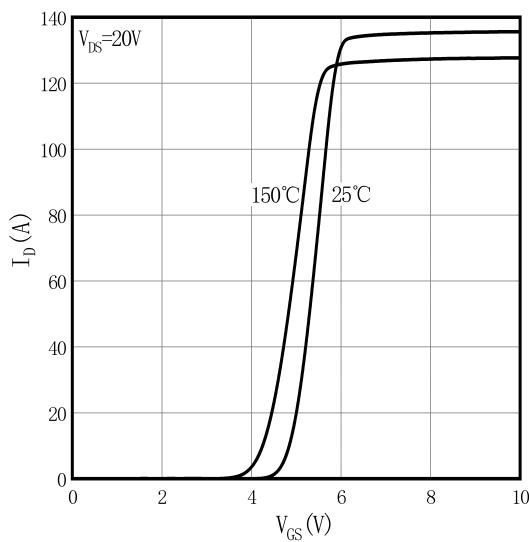


Figure 3. On-Resistance vs. Drain Current

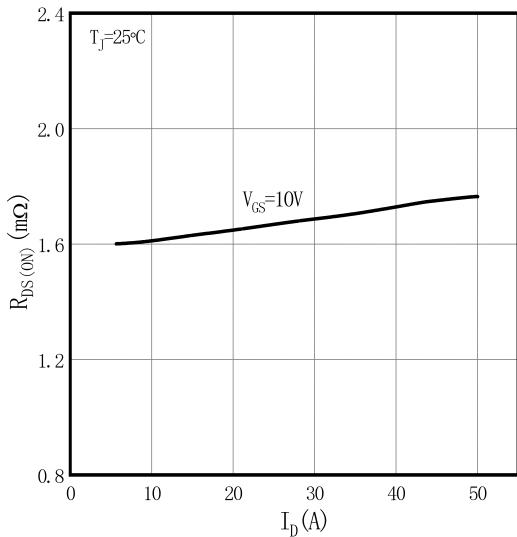


Figure 4. On-Resistance vs. Temperature

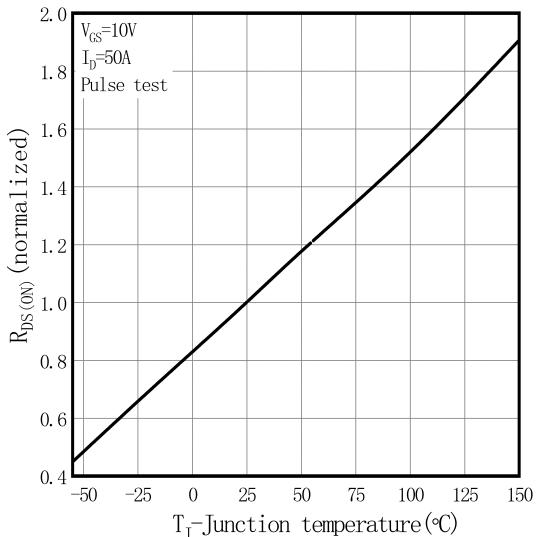


Figure 5. Breakdown Voltage vs. Temperature

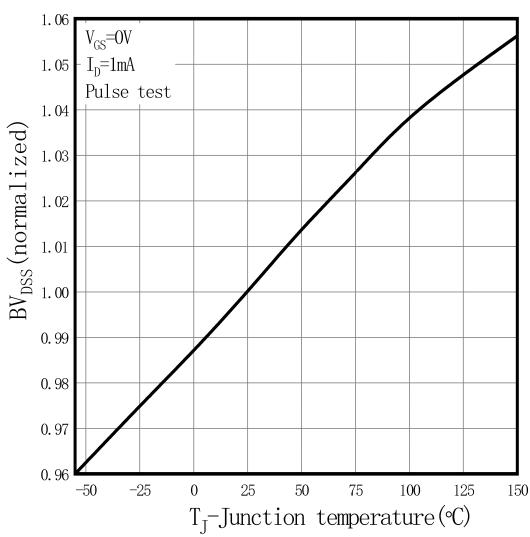


Figure 6. Threshold Voltage vs. Temperature

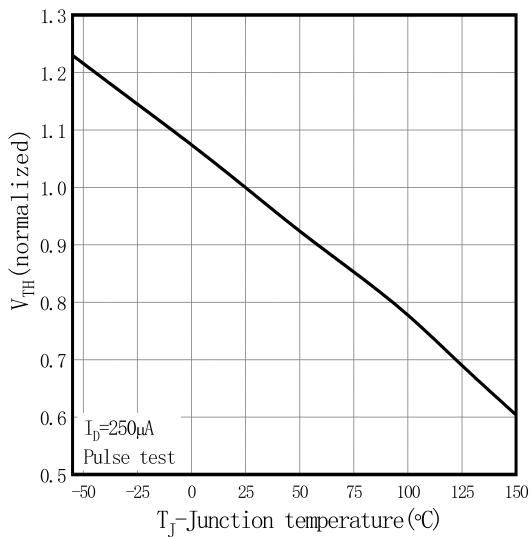


Figure 7.Rds(on) vs. Gate Voltage

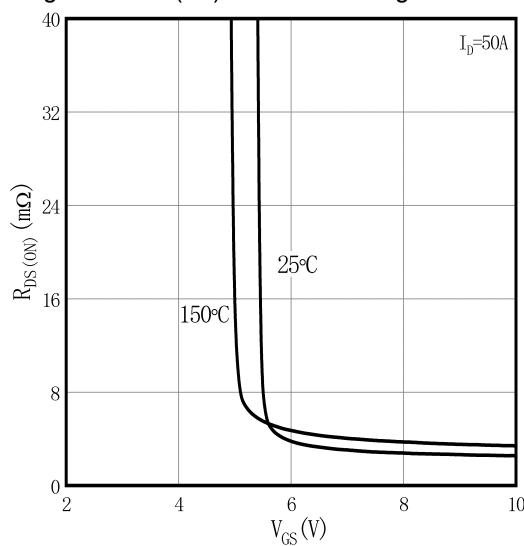


Figure 8.Body-Diode Characteristics

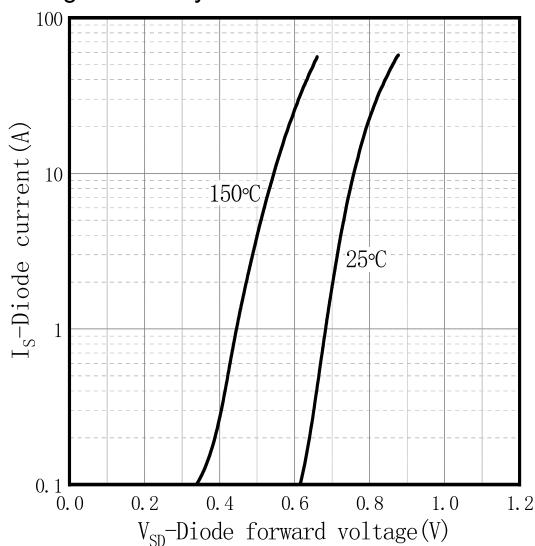


Figure 9.Capacitance Characteristics

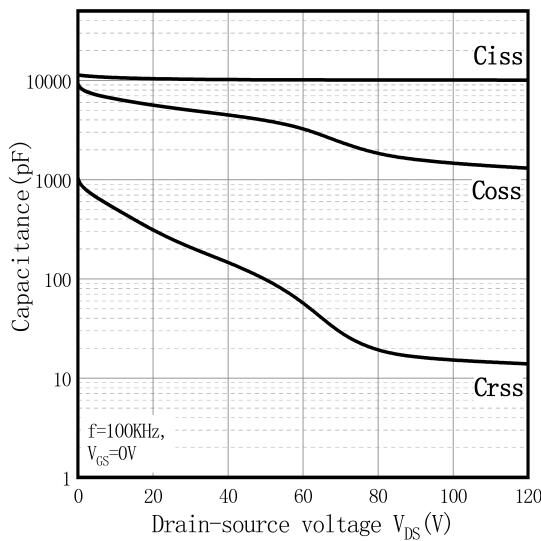


Figure 10.Gate Charge Characteristics

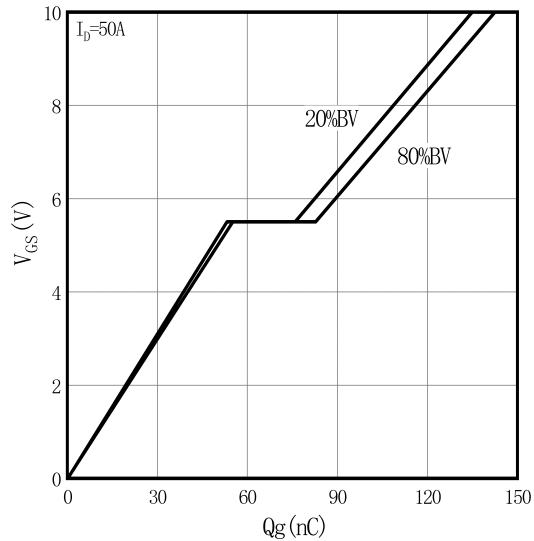


Figure 11.Drain Current Derating

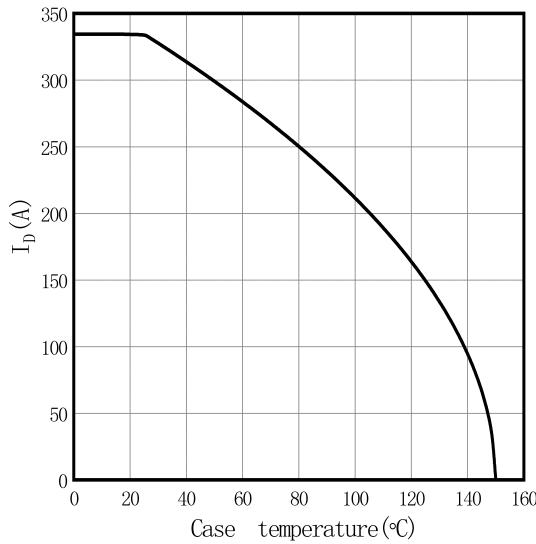


Figure 12.Power Dissipation vs.Temperature

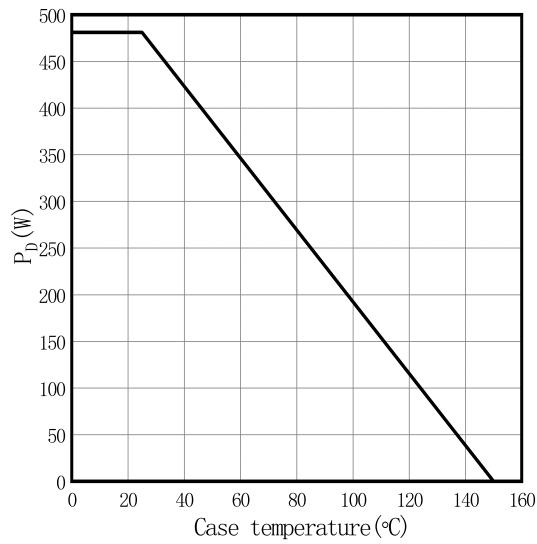


Figure 13. Safe Operating Area

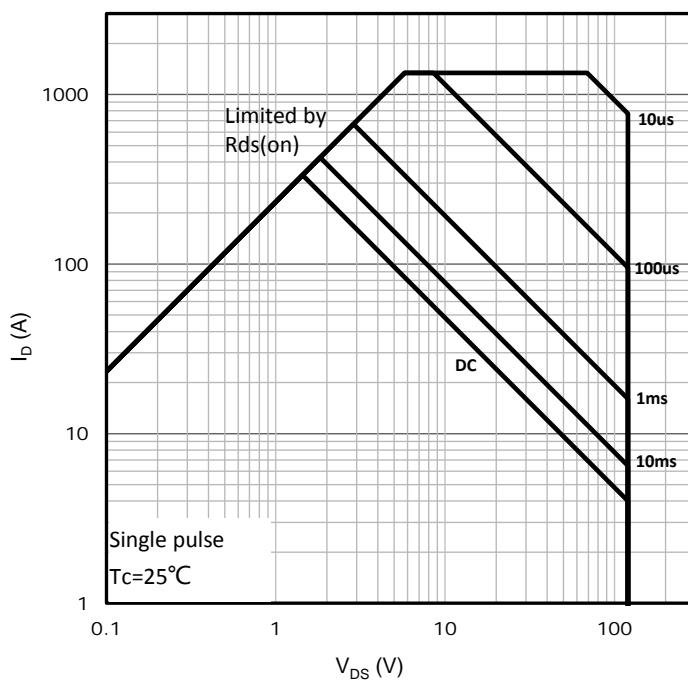
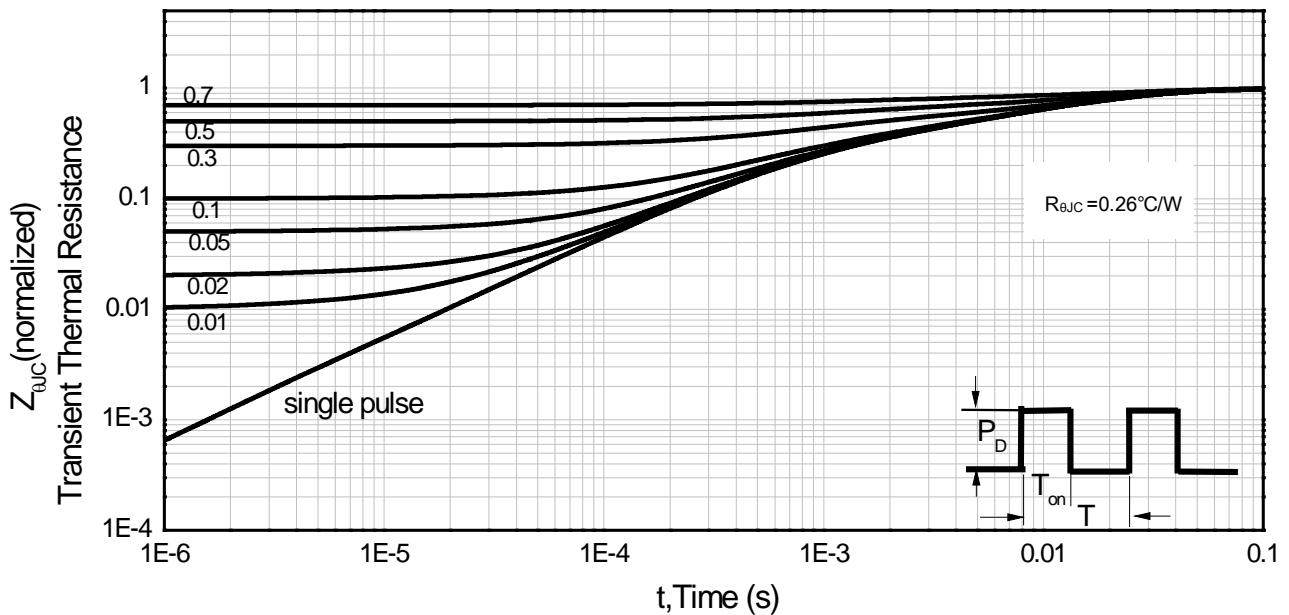
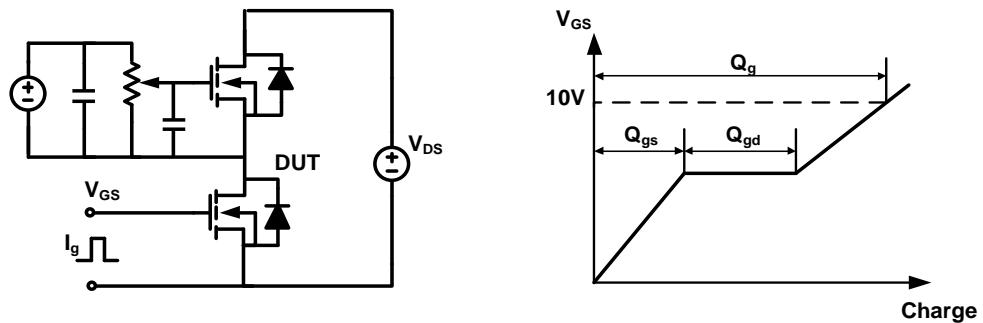


Figure 14. Normalized Maximum Transient Thermal Impedance (R_{thJC})

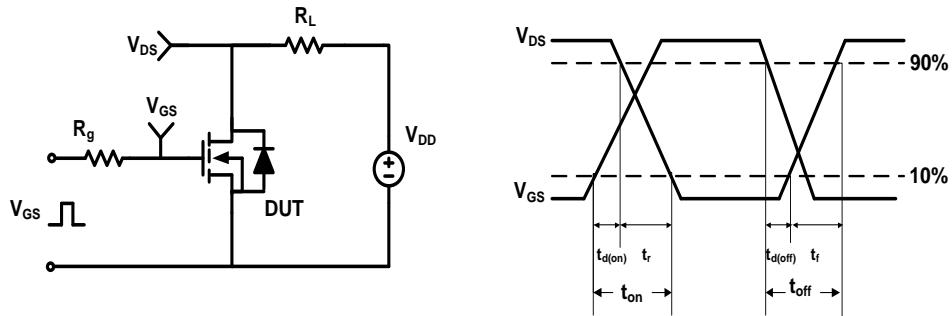


Test Circuit & Waveforms

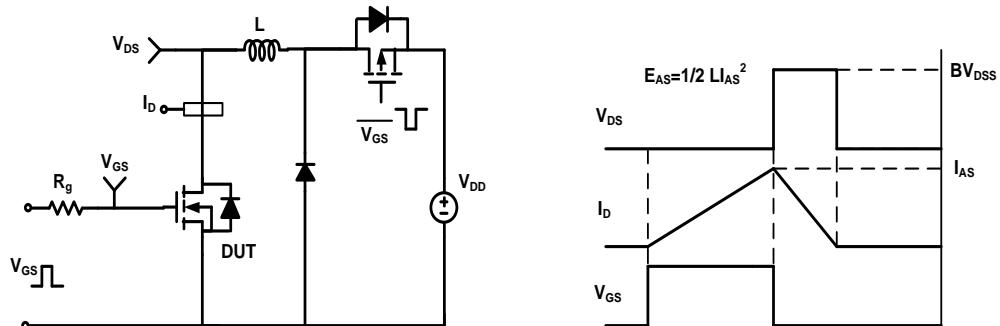
Gate Charge Test Circuit & Waveform



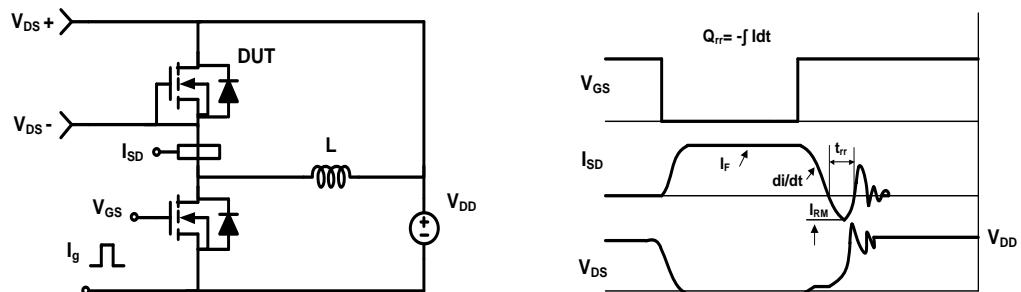
Resistive Switching Test Circuit & Waveform

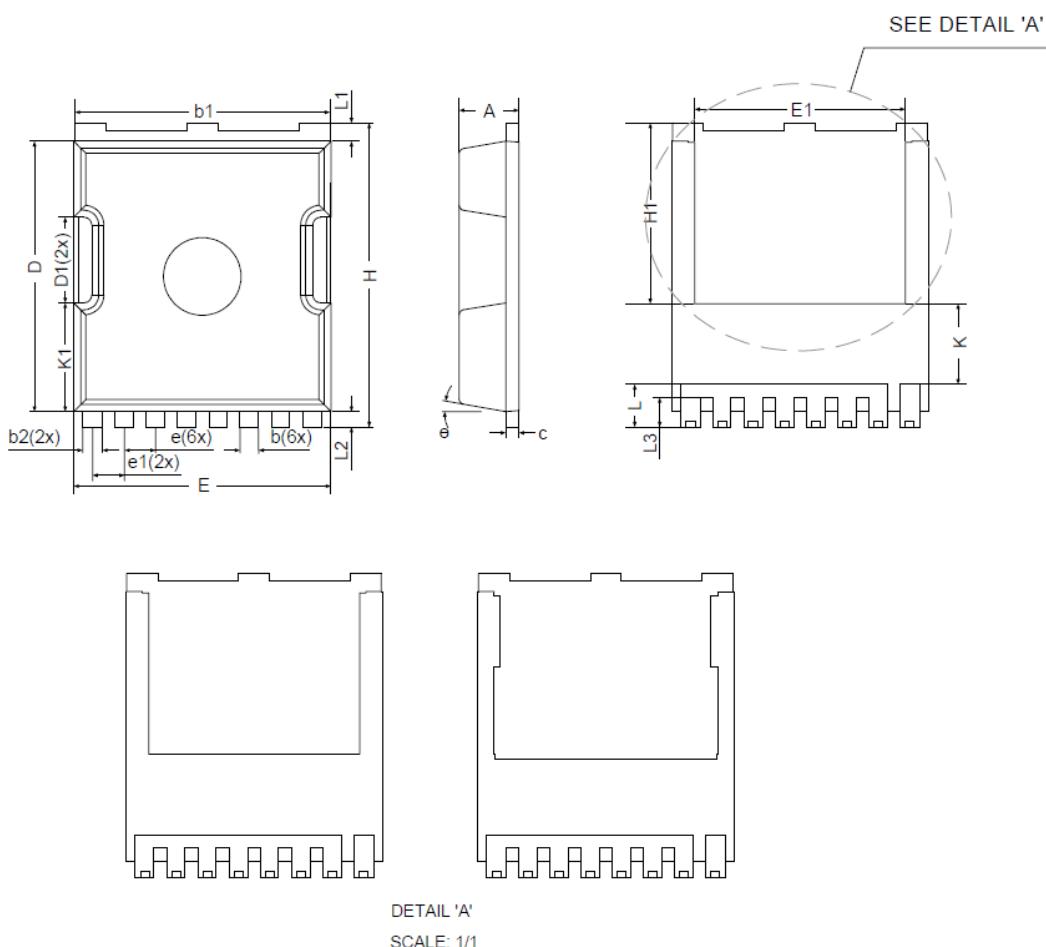


Unclamped Inductive Switching (UIS) Test Circuit & Waveform



Diode Recovery Test Circuit & Waveform



Mechanical Dimensions for TOLL


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.15	2.45	0.085	0.096
b	0.60	0.90	0.024	0.035
b1	9.65	9.95	0.380	0.392
b2	0.65	0.90	0.026	0.035
c	0.40	0.60	0.016	0.024
D	10.18	10.58	0.401	0.417
D1	3.15	3.45	0.124	0.136
E	9.70	10.10	0.382	0.398
E1	7.90	8.40	0.311	0.331
e	1.10	1.30	0.043	0.051
e1	1.10	1.30	0.043	0.051
H	11.48	11.88	0.452	0.468
H1	6.75	7.30	0.266	0.287
K	2.45	3.33	0.096	0.131
K1	4.03	4.33	0.159	0.170
L	1.50	2.10	0.059	0.083
L1	0.50	0.90	0.020	0.035
L2	0.45	0.75	0.018	0.030
L3	1.00	1.30	0.039	0.051
θ	10° REF		10° REF	

Revision History

LSGT12R022

Revision 1.0

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